



3D Packaging & Integration North America TC Chapter

NA Standards Fall Meetings 2019

Thursday, November 7

SEMI Headquarters, Milpitas, California

14:00–16:00

AGENDA

1 Welcome/Call to Order

- 1.1 Introductions
- 1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)
- 1.3 Agenda Review

2 Review of Previous Meeting Minutes

3 Liaison Report

- 3.1 Japan TC Chapter
- 3.2 Taiwan TC Chapter

4 Staff Report

5 Ballot Review

- 5.1 Document 6555 — Reapproval of SEMI 3D9-0914, Guide for Describing Materials Properties for a 300 mm 3DS-IC Wafer Stack
- 5.2 Document 6556 — Reapproval of SEMI 3D10-0814, Guide to Describing Materials Properties for Intermediate Wafers for Use in a 300 mm 3DS-IC Wafer Stack
- 5.3 Document 6557 — Reapproval of SEMI 3D11-1214, Terminology for Through Glass Via and Blind Via in Glass Geometrical Metrology
- 5.4 Document 6558 — Reapproval of SEMI 3D12-0315, Guide for Measuring Flatness and Shape of Low Stiffness Wafers

6 Task Force Reports

- 6.1 Joint Bonded Wafer Stacks Task Force & Inspection & Metrology Task Forces
- 6.2 Panel Level Packaging Panel Task Force



7 Old Business

7.1 Standards due for Five-Year Review

- SEMI 3D13-0715, Guide for Measuring Voids in Bonded Wafer Stacks
- SEMI 3D4-0915, Guide for Metrology for Measuring Thickness, Total Thickness Variation (TTV), Bow, Warp/Sori, and Flatness of Bonded Wafer Stacks

8 New Business

8.1 New SNARF(s) and/or TFOF(s)

9 Action Item Review

9.1 Open Action Items (*none*)

9.2 New Action Items

10 Next Meeting and Adjournment

- 10.1 The next meeting is scheduled for Thursday, April 2, in conjunction with the NA Standards Spring 2020 Meetings at SEMI Headquarters in Milpitas, California.

Tentative Schedule:

Thursday, April 2

10:00-12:00 Joint 3DP&I Bonded Wafer Stacks (TF) and 3DP&I Inspection and Metrology (TF)

13:00-14:00 PLP Panel (TF)

14:00-16:00 3DP&I (C)

Note: Alternative to move to another day?

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